

74AXP2T3407

Dual supply single buffer and single buffer with open-drain

Rev. 1 — 21 December 2015

Product data sheet

1. General description

The 74AXP2T3407 is a dual supply single buffer and a single buffer with open-drain output. It features two input pins (nA), an output pin (1Y) and an open-drain output pin (2Y) and dual supply pins (V_{CCI} and V_{CCO}). The inputs are referenced to V_{CCI} and the output is referenced to V_{CCO} . All inputs can be connected directly to V_{CCI} or GND. V_{CCI} can be supplied at any voltage between 0.7 V and 2.75 V and V_{CCO} can be supplied at any voltage between 1.2 V and 5.5 V. This feature allows voltage level translation.

Schmitt-trigger action at all inputs makes the circuit tolerant of slower input rise and fall times.

This device ensures very low static and dynamic power consumption across the entire supply range and is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range:
 - ◆ V_{CCI} : 0.7 V to 2.75 V
 - ◆ V_{CCO} : 1.2 V to 5.5 V
- Low input capacitance; $C_I = 0.6$ pF (typical)
- Low output capacitance; $C_O = 1.8$ pF (typical) for 1Y
- Low output capacitance; $C_O = 1.3$ pF (typical) for 2Y
- Low dynamic power consumption; $C_{PD} = 0.4$ pF at $V_{CCI} = 1.2$ V (typical)
- Low dynamic power consumption; $C_{PD} = 7.1$ pF at $V_{CCO} = 3.3$ V (typical)
- Low static power consumption; $I_{CCI} = 0.5$ μ A (85 °C maximum)
- Low static power consumption; $I_{CCO} = 1.8$ μ A (85 °C maximum)
- High noise immunity
- Complies with JEDEC standard:
 - ◆ JESD8-12A.01 (1.1 V to 1.3 V; nA inputs)
 - ◆ JESD8-11A.01 (1.4 V to 1.6 V)
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A.01 (2.3 V to 2.7 V)
 - ◆ JESD8-C (2.7 V to 3.6 V; nY outputs)
 - ◆ JESD12-6 (4.5 V to 5.5 V; nY outputs)
- ESD protection:
 - ◆ HBM ANSI/ESDA/JEDEC JS-001 Class 2 exceeds 2 kV
 - ◆ CDM JESD22-C101E exceeds 1000 V



- Latch-up performance exceeds 100 mA per JESD78D Class II
- Inputs accept voltages up to 2.75 V
- Low noise overshoot and undershoot < 10% of V_{CCO}
- I_{OFF} circuitry provides partial power-down mode operation
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AXP2T3407DP	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm	SOT505-2
74AXP2T3407DC	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm	SOT765-1
74AXP2T3407GT	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body $1 \times 1.95 \times 0.5$ mm	SOT833-1
74AXP2T3407GD	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body $3 \times 2 \times 0.5$ mm	SOT996-2
74AXP2T3407GN	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	XSON8	extremely thin small outline package; no leads; 8 terminals; body $1.2 \times 1.0 \times 0.35$ mm	SOT1116
74AXP2T3407GS	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	XSON8	extremely thin small outline package; no leads; 8 terminals; body $1.35 \times 1.0 \times 0.35$ mm	SOT1203

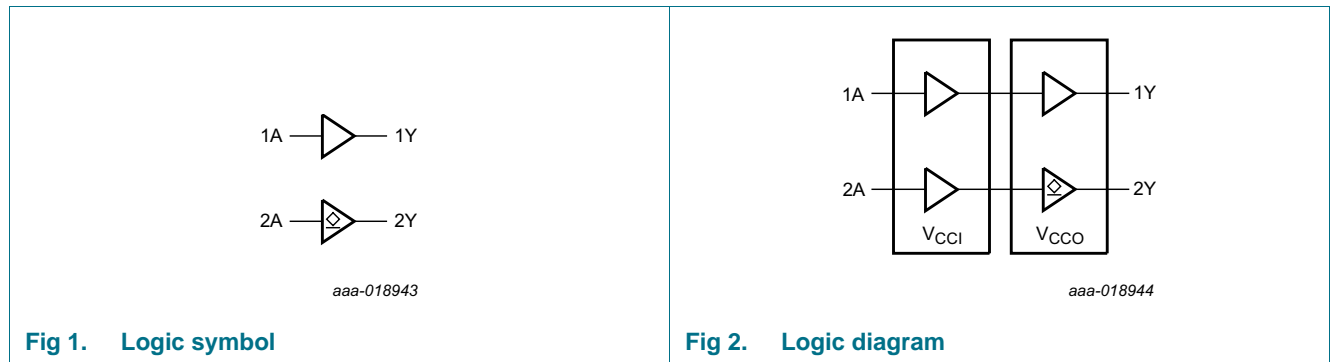
4. Marking

Table 2. Marking

Type number	Marking code ^[1]
74AXP2T3407DP	r4
74AXP2T3407DC	r4
74AXP2T3407GT	r4
74AXP2T3407GD	r4
74AXP2T3407GN	r4
74AXP2T3407GS	r4

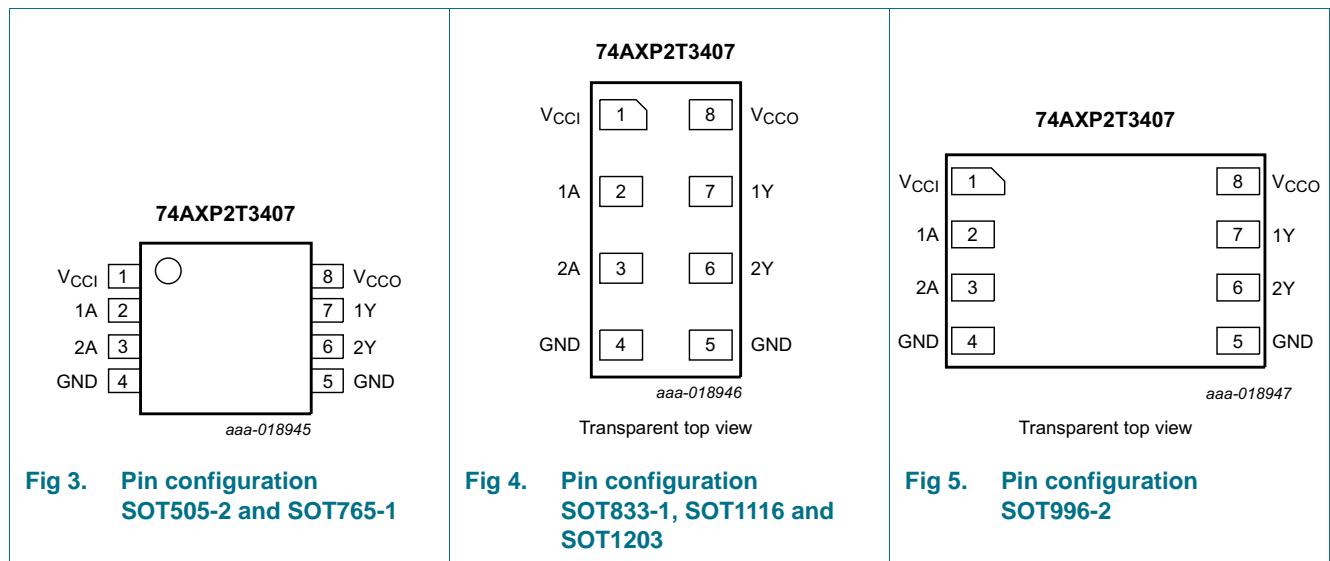
[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram



6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
V _{CCI}	1	input supply voltage
1A	2	data input
2A	3	data input
GND ^[1]	4, 5	ground (0 V)
2Y	6	data output (open-drain)
1Y	7	data output
V _{CCO}	10	output supply voltage

[1] All GND pins must be connected to ground (0 V).

7. Functional description

Table 4. Function table^[1]

Supply voltage		Input		Output
V _{CCI}	V _{CCO}	1A		1Y
0.7 V to 2.75 V	1.2 V to 5.5 V	L		L
0.7 V to 2.75 V	1.2 V to 5.5 V	H		H
GND	1.2 V to 5.5 V	X		Z
0.7 V to 2.75 V	GND	X		Z
GND	GND	X		Z

[1] H = HIGH voltage level; L = LOW voltage level.

Table 5. Function table^[1]

Supply voltage		Input		Output
V _{CCI}	V _{CCO}	2A		2Y
0.7 V to 2.75 V	1.2 V to 5.5 V	L		L
0.7 V to 2.75 V	1.2 V to 5.5 V	H		Z
GND	1.2 V to 5.5 V	X		Z
0.7 V to 2.75 V	GND	X		Z
GND	GND	X		Z

[1] H = HIGH voltage level; L = LOW voltage level.

8. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCI}	input supply voltage		-0.5	3.3	V
V _{CCO}	output supply voltage		-0.5	6.0	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage		-0.5	3.3	V
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
V _O	output voltage	Active mode	-0.5	V _{CCO} + 0.5	V
		Power-down or 3-state mode	-0.5	6.0	V
I _O	output current	V _O = 0 V to V _{CCO}	-	±25	mA
I _{CCI}	input supply current		-	50	mA
I _{CCO}	output supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +85 °C	-	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] V_{CCO} + 0.5 V should not exceed 6.0 V.

[3] For SOT833-1 package: above 70 °C the value of P_{tot} derates linearly with 3.2 mW/K.
For SOT1203 package: above 80 °C the value of P_{tot} derates linearly with 3.6 mW/K.

9. Recommended operating conditions

Table 7. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCI}	input supply voltage		0.7	2.75	V
V _{CCO}	output supply voltage		1.2	5.5	V
V _I	input voltage		0	2.75	V
V _O	output voltage	Active mode	0	V _{CCO}	V
		Power-down or 3-state mode	0	5.5	V
T _{amb}	ambient temperature		-40	+85	°C
Δt/ΔV	input transition rise and fall rate	V _{CCI} = 0.7 V to 2.75 V	0	200	ns/V

10. Static characteristics

Table 8. Static characteristics

At recommended operating conditions, unless otherwise specified; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T _{amb} = -40 °C to +85 °C				Unit
			Min	Typ 25 °C	Max 25 °C	Max 85 °C	
V _{IH}	HIGH-level input voltage	V _{CCI} = 0.75 V to 0.85 V	0.75V _{CCI}	-	-	-	V
		V _{CCI} = 1.1 V to 1.95 V	0.65V _{CCI}	-	-	-	V
		V _{CCI} = 2.3 V to 2.7 V	1.6	-	-	-	V
V _{IL}	LOW-level input voltage	V _{CCI} = 0.75 V to 0.85 V	-	-	0.25V _{CCI}	0.25V _{CCI}	V
		V _{CCI} = 1.1 V to 1.95 V	-	-	0.35V _{CCI}	0.35V _{CCI}	V
		V _{CCI} = 2.3 V to 2.7 V	-	-	0.7	0.7	V
V _{OH}	HIGH-level output voltage	I _O = -2 mA; V _{CCO} = 1.2 V [1]	-	1.05	-	-	V
		I _O = -3 mA; V _{CCO} = 1.4 V	1.05	-	-	-	V
		I _O = -4.5 mA; V _{CCO} = 1.65 V	1.2	-	-	-	V
		I _O = -8 mA; V _{CCO} = 2.3 V	1.7	-	-	-	V
		I _O = -10 mA; V _{CCO} = 3.0 V	2.2	-	-	-	V
		I _O = -12 mA; V _{CCO} = 4.5 V	3.7	-	-	-	V
V _{OL}	LOW-level output voltage	I _O = 2 mA; V _{CCO} = 1.2 V [1]	-	0.18	-	-	V
		I _O = 3 mA; V _{CCO} = 1.4 V	-	-	0.35	0.35	V
		I _O = 4.5 mA; V _{CCO} = 1.65 V	-	-	0.45	0.45	V
		I _O = 8 mA; V _{CCO} = 2.3 V	-	-	0.7	0.7	V
		I _O = 10 mA; V _{CCO} = 3.0 V	-	-	0.8	0.8	V
		I _O = 12 mA; V _{CCO} = 4.5 V	-	-	0.8	0.8	V
I _I	input leakage current	V _I = 0 V to 2.75 V; V _{CCI} = 0 V to 2.75 V [1]	-	±0.001	±0.1	±0.5	µA
I _{OZ}	OFF-state output current	V _O = 0 V to 5.5 V; V _{CCO} = 1.2 V to 5.5 V	-	±0.001	±0.1	±0.5	µA
I _{OFF}	power-off leakage current	inputs; V _I = 0 V to 2.75 V; V _{CCI} = 0 V; V _{CCO} = 0 V to 5.5 V [1]	-	±0.01	±0.1	±0.5	µA
		output; V _O = 0 V to 5.5 V; V _{CCO} = 0 V; V _{CCI} = 0 V to 2.75 V; V _I = 0 V to 2.75 V [1]	-	±0.01	±0.1	±0.5	µA
ΔI _{OFF}	additional power-off leakage current	inputs; V _I = 0 V or 2.75 V; V _{CCI} = 0 V to 0.1 V; V _{CCO} = 0 V to 5.5 V [1]	-	±0.02	±0.1	±0.5	µA
		output; V _O = 0 V or 5.5 V; V _{CCO} = 0 V to 0.1 V; V _{CCI} = 0 V to 2.75 V; V _I = 0 V or 2.75 V [1]	-	±0.02	±0.1	±0.5	µA

[1] Typical values are measured at V_{CCI} = V_{CCO} = 1.2 V unless otherwise specified.

Table 9. Static characteristics supply current

At recommended operating conditions, unless otherwise specified; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T _{amb} = -40 °C to +85 °C				Unit
			Typ 25 °C	Max 25 °C	Typ 85 °C	Max 85 °C	
I _{CCI}	input supply current	V _I = 0 V or V _{CCI} ;					
		V _{CCI} = 0.7 V to 1.3 V [1]	1	100	10	300	nA
		V _{CCI} = 1.3 V to 2.75 V [2]	1	100	20	500	nA
		V _{CCI} = 2.75 V; V _{CCO} = 0 V	1	100	20	500	nA
		V _{CCI} = 0 V; V _{CCO} = 5.5 V	1	100	1	100	nA
I _{CCO}	output supply current	V _I = 0 V or V _{CCI} ; I _O = 0 A; see Table 10					
		V _{CCO} = 1.2 V to 3.6 V [1]	0.001	1.0	0.01	1.2	μA
		V _{CCO} = 3.6 V to 5.5 V [3]	0.8	1.5	1.0	1.8	μA
		V _{CCI} = 2.75 V; V _{CCO} = 0 V	0.001	0.1	0.003	0.2	μA
		V _{CCI} = 0 V; V _{CCO} = 3.6 V	0.2	0.6	0.3	0.8	μA
		V _{CCI} = 0 V; V _{CCO} = 5.5 V	0.4	0.8	0.5	1.0	μA
ΔI _{CCI}	additional input supply current	V _I = V _{CCI} - 0.5 V; V _{CCI} = 2.5 V	2	100	14	150	μA

[1] Typical values are measured at V_{CCI} = V_{CCO} = 1.2 V.

[2] Typical values are measured at V_{CCI} = V_{CCO} = 2.5 V.

[3] Typical values are measured at V_{CCI} = 1.2 V and V_{CCO} = 5.0 V.

Table 10. Typical output supply current (I_{CCO})

V _{CCI}	V _{CCO}							Unit
	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V	
0 V	0	1	5	20	100	200	400	nA
0.8 V	1	10	150	200	300	500	800	nA
1.2 V	1	1	5	200	300	500	800	nA
1.5 V	1	1	5	100	300	500	800	nA
1.8 V	1	1	5	100	300	500	800	nA
2.5 V	1	1	5	100	100	500	800	nA

11. Dynamic characteristics

Table 11. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 13](#); for wave form see [Figure 6](#).

Symbol	Parameter	Conditions	V _{CC0}						Unit	
			1.2 V	1.5 V ± 0.1 V		1.8 V ± 0.15 V				
			Typ ^[1]	Min	Typ ^[1]	Max	Min	Typ ^[1]		Max
T_{amb} = 25 °C										
t _{pd}	propagation delay	nA to nY ^[2]								
		V _{CCI} = 0.75 V to 0.85 V	22.1	3	17	76	3	15	72	ns
		V _{CCI} = 1.1 V to 1.3 V	15.8	3.1	10.3	19.8	2.8	8.3	15.8	ns
		V _{CCI} = 1.4 V to 1.6 V	14.9	2.8	9.4	18.2	2.5	7.4	13.3	ns
		V _{CCI} = 1.65 V to 1.95 V	14.5	2.7	9.0	17.4	2.4	7.0	12.9	ns
		V _{CCI} = 2.3 V to 2.7 V	14.1	2.5	8.6	16.9	2.2	6.6	12.2	ns
T_{amb} = -40 °C to +85 °C										
t _{pd}	propagation delay	nA to nY ^[2]								
		V _{CCI} = 0.75 V to 0.85 V	22.1	3	17	151	3	15	148	ns
		V _{CCI} = 1.1 V to 1.3 V	15.8	3.1	10.3	19.8	2.8	8.3	15.8	ns
		V _{CCI} = 1.4 V to 1.6 V	14.9	2.8	9.4	18.2	2.5	7.4	13.3	ns
		V _{CCI} = 1.65 V to 1.95 V	14.5	2.7	9.0	17.4	2.4	7.0	12.9	ns
		V _{CCI} = 2.3 V to 2.7 V	14.1	2.5	8.6	16.9	2.2	6.6	12.2	ns
t _t	transition time	V _{CCI} = 0.75 V to 2.7 V ^[3]	-	1.0	-	-	1.0	-	-	ns

[1] Typical values are measured at nominal supply voltages and T_{amb} = +25 °C.

[2] t_{pd} is the same as t_{PLH} and t_{PHL} (1A to 1Y) and t_{PLZ} and t_{PZL} (2A to 2Y).

[3] t_t is the same as t_{THL} and t_{TLH} (1A to 1Y) and t_{PZL} (2A to 2Y).

Table 12. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 13](#); for wave form see [Figure 6](#).

Symbol	Parameter	Conditions	V _{CC0}									Unit
			2.5 V ± 0.2 V			3.3 V ± 0.3 V			5.0 V ± 0.5 V			
			Min	Typ ^[1]	Max	Min	Typ ^[1]	Max	Min	Typ ^[1]	Max	
T_{amb} = 25 °C												
t _{pd}	propagation delay	nA to nY ^[2]										
		V _{CCI} = 0.75 V to 0.85 V	2	13	72	2	13	80	2	14	92	ns
		V _{CCI} = 1.1 V to 1.3 V	2.4	6.6	11.4	2.2	5.9	12.2	2.1	5.5	10.1	ns
		V _{CCI} = 1.4 V to 1.6 V	2.1	5.7	10.1	2.0	5.0	10.9	1.9	4.6	8.9	ns
		V _{CCI} = 1.65 V to 1.95 V	2.0	5.3	9.5	1.8	4.6	10.3	1.8	4.2	8.3	ns
		V _{CCI} = 2.3 V to 2.7 V	1.9	4.9	9.0	1.7	4.2	9.8	1.6	3.8	7.8	ns
T_{amb} = -40 °C to +85 °C												
t _{pd}	propagation delay	nA to nY ^[2]										
		V _{CCI} = 0.75 V to 0.85 V	2	13	167	2	13	194	2	14	225	ns
		V _{CCI} = 1.1 V to 1.3 V	2.4	6.6	11.4	2.2	5.9	12.2	2.1	5.5	10.1	ns
		V _{CCI} = 1.4 V to 1.6 V	2.1	5.7	10.1	2.0	5.0	10.9	1.9	4.6	8.9	ns
		V _{CCI} = 1.65 V to 1.95 V	2.0	5.3	9.5	1.8	4.6	10.3	1.8	4.2	8.3	ns
		V _{CCI} = 2.3 V to 2.7 V	1.9	4.9	9.0	1.7	4.2	9.8	1.6	3.8	7.8	ns
t _t	transition time	V _{CCI} = 0.75 V to 2.7 V ^[3]	1.0	-	-	1.0	-	-	1.0	-	-	ns

[1] Typical values are measured at nominal supply voltages and t_{amb} = +25 °C.

[2] t_{pd} is the same as t_{PLH} and t_{PHL} (1A to 1Y) and t_{PLZ} and t_{PZL} (2A to 2Y).

[3] t_t is the same as t_{THL} and t_{TLH} (1A to 1Y) and t_{PZL} (2A to 2Y).

Table 13. Typical dynamic characteristics at $T_{amb} = 25\text{ °C}$

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 13](#); for wave form see [Figure 6](#).

Symbol	Parameter	Conditions	V_{CCO}						Unit	
			1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V		
C_{PD}	power dissipation capacitance	$f_i = 1\text{ MHz}$; $R_L = \infty\ \Omega$; $V_I = 0\text{ V to }V_{CCI}$ [1]								
		1A, 2A; input supply [2]								
		$V_{CCI} = 0.8\text{ V}$	0.4	0.4	0.4	0.4	0.4	0.4	pF	
		$V_{CCI} = 1.2\text{ V}$	0.4	0.4	0.4	0.4	0.4	0.4	pF	
		$V_{CCI} = 1.5\text{ V}$	0.5	0.5	0.5	0.5	0.5	0.5	pF	
		$V_{CCI} = 1.8\text{ V}$	0.5	0.5	0.5	0.5	0.5	0.5	pF	
		$V_{CCI} = 2.5\text{ V}$	0.7	0.7	0.7	0.7	0.7	0.7	pF	
		1Y; output supply [3]								
		$V_{CCO} = 0.8\text{ V}$	6.7	6.8	6.8	6.9	7.5	9.5	pF	
		$V_{CCO} = 1.2\text{ V}$	6.8	6.9	7.0	7.0	7.1	7.6	pF	
		$V_{CCO} = 1.5\text{ V}$	6.9	6.9	6.9	7.0	7.1	7.6	pF	
		$V_{CCO} = 1.8\text{ V}$	6.9	6.9	6.9	7.0	7.2	7.6	pF	
		$V_{CCO} = 2.5\text{ V}$	6.9	7.0	7.0	7.0	7.2	7.6	pF	
		2Y; output supply [3]								
		$V_{CCO} = 0.8\text{ V}$	2.1	2.2	2.2	2.2	2.3	2.8	pF	
		$V_{CCO} = 1.2\text{ V}$	2.2	2.3	2.4	2.3	2.4	2.5	pF	
		$V_{CCO} = 1.5\text{ V}$	2.3	2.3	2.3	2.4	2.4	2.5	pF	
		$V_{CCO} = 1.8\text{ V}$	2.3	2.3	2.3	2.4	2.4	2.5	pF	
		$V_{CCO} = 2.5\text{ V}$	2.3	2.3	2.3	2.3	2.4	2.6	pF	
C_I	input capacitance	$V_I = 0\text{ V or }V_{CCI}$; $V_{CCI} = 0\text{ V to }2.7\text{ V}$	0.6	0.6	0.6	0.6	0.6	0.6	pF	
C_O	output capacitance	2Y; $V_O = 0\text{ V}$; $V_{CCO} = 0\text{ V}$	1.3	1.3	1.3	1.3	1.3	1.3	pF	
		1Y; $V_O = 0\text{ V}$; $V_{CCO} = 0\text{ V}$	1.8	1.8	1.8	1.8	1.8	1.8	pF	

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

[2] Power dissipated from input supply (V_{CCI})

$$P_D = C_{PD} \times V_{CCI}^2 \times f_i \times N \text{ where:}$$

C_{PD} = power dissipation capacitance of the input supply.

V_{CCI} = input supply voltage in V;

f_i = input frequency in MHz;

N = number of inputs switching;

[3] Power dissipated from output supply (V_{CCO})

$$P_D = (C_L + C_{PD}) \times V_{CCO}^2 \times f_o \text{ where:}$$

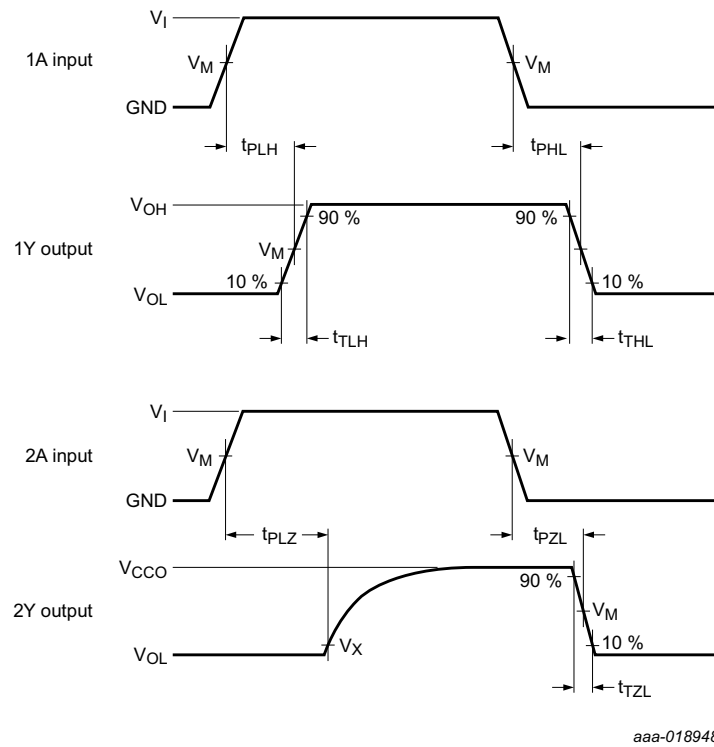
C_L = load capacitance in pF;

C_{PD} = power dissipation capacitance of the output supply.

V_{CCO} = output supply voltage in V;

f_o = output frequency in MHz;

11.1 Waveforms and graphs



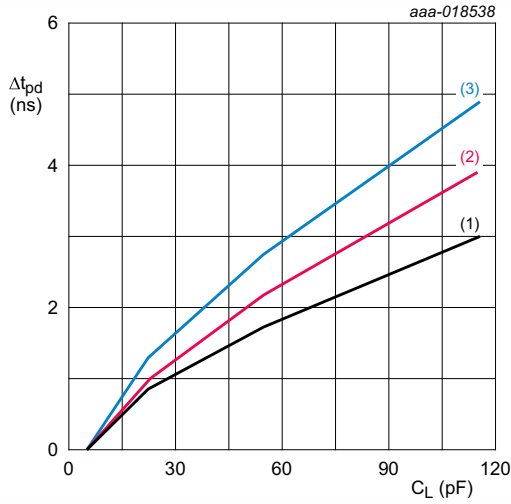
Measurement points are given in [Table 14](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. Input nA to output nY propagation delay times and output transition times

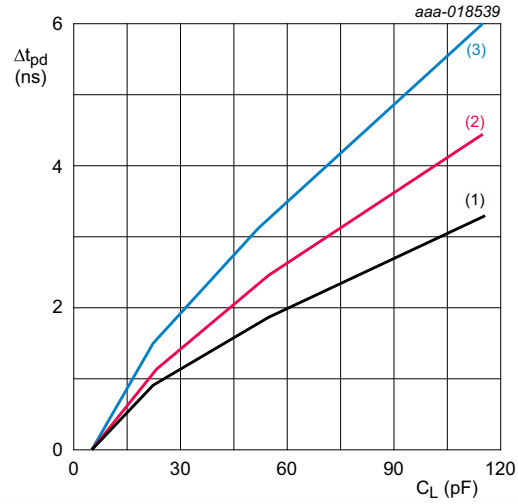
Table 14. Measurement points

Supply voltage		Output		Input	
V_{CCI}	V_{CCO}	V_M	V_X	V_M	V_I
0.75 V to 2.7 V	1.2 V to 1.6 V	$0.5V_{CCO}$	$V_{OL} + 0.1 V$	$0.5V_{CCI}$	V_{CCI}
0.75 V to 2.7 V	1.65 V to 2.7 V	$0.5V_{CCO}$	$V_{OL} + 0.15 V$	$0.5V_{CCI}$	V_{CCI}
0.75 V to 2.7 V	3.0 V to 5.5 V	$0.5V_{CCO}$	$V_{OL} + 0.3 V$	$0.5V_{CCI}$	V_{CCI}



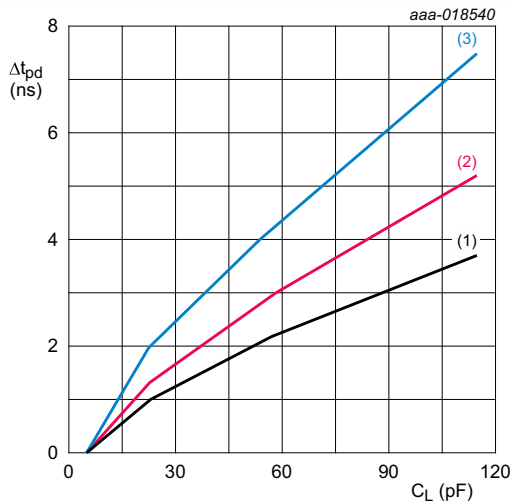
$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
 For t_{PLH} , t_{PHL} and t_{PZL}
 (1) Minimum: $V_{CCO} = 5.5\text{ V}$
 (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CCO} = 5\text{ V}$
 (3) Maximum: $V_{CCO} = 4.5\text{ V}$

Fig 7. Additional propagation delay versus load capacitance



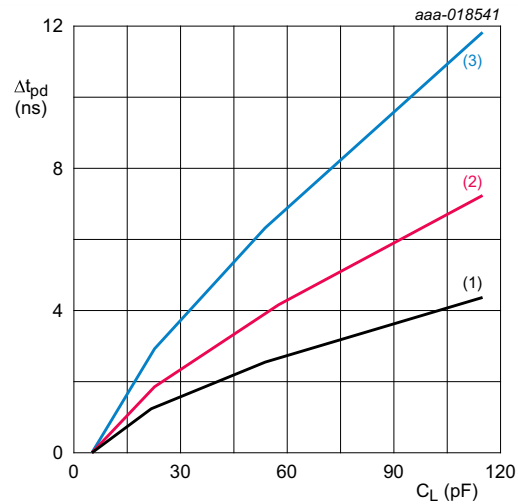
$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
 For t_{PLH} , t_{PHL} and t_{PZL}
 (1) Minimum: $V_{CCO} = 3.6\text{ V}$
 (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CCO} = 3.3\text{ V}$
 (3) Maximum: $V_{CCO} = 3\text{ V}$

Fig 8. Additional propagation delay versus load capacitance



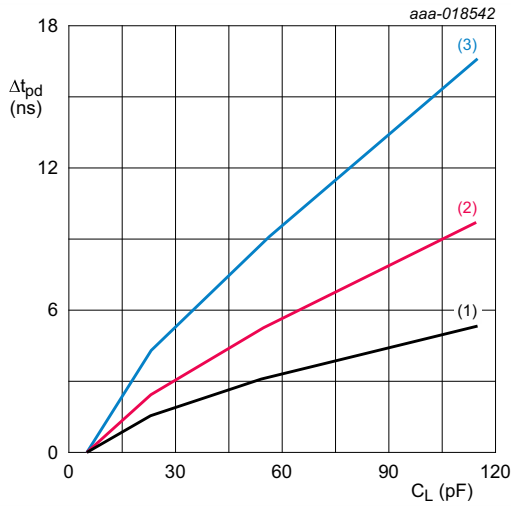
$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
 For t_{PLH} , t_{PHL} and t_{PZL}
 (1) Minimum: $V_{CCO} = 2.7\text{ V}$
 (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CCO} = 2.5\text{ V}$
 (3) Maximum: $V_{CCO} = 2.3\text{ V}$

Fig 9. Additional propagation delay versus load capacitance



$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
 For t_{PLH} , t_{PHL} and t_{PZL}
 (1) Minimum: $V_{CCO} = 1.95\text{ V}$
 (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CCO} = 1.8\text{ V}$
 (3) Maximum: $V_{CCO} = 1.65\text{ V}$

Fig 10. Additional propagation delay versus load capacitance

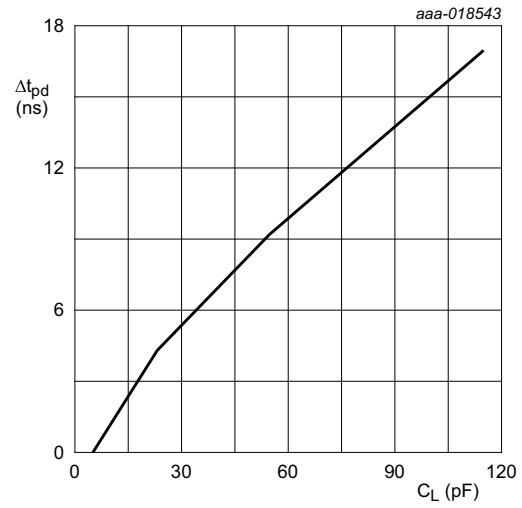


$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.

For t_{PLH} , t_{PHL} and t_{PZL}

- (1) Minimum: $V_{CCO} = 1.6\text{ V}$
- (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CCO} = 1.5\text{ V}$
- (3) Maximum: $V_{CCO} = 1.4\text{ V}$

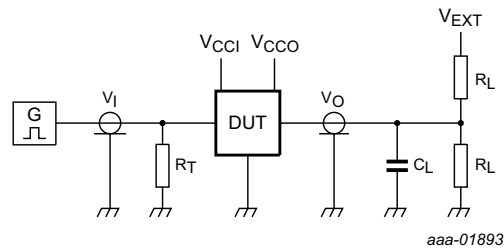
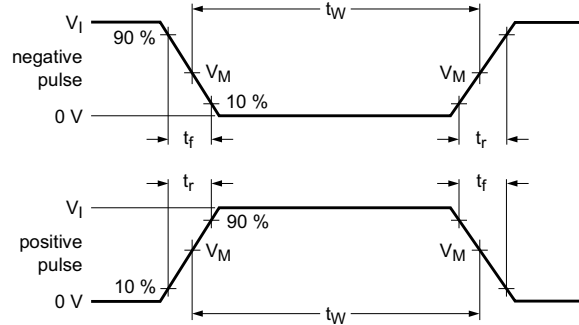
Fig 11. Additional propagation delay versus load capacitance



$T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CCO} = 1.2\text{ V}$.

For t_{PLH} , t_{PHL} and t_{PZL}

Fig 12. Additional propagation delay versus load capacitance



aaa-018932

Test data is given in [Table 15](#).

Definitions test circuit:

R_T = termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = load capacitance including jig and probe capacitance.

R_L = Load resistance.

Fig 13. Test circuit for measuring switching times

Table 15. Test data

Supply voltage		Load		Input		V_{EXT}	
V_{CCI}	V_{CCO}	C_L	R_L	t_r, t_f	V_I	t_{PLH}, t_{PHL}	t_{PZL}, t_{PLZ}
0.75 V to 2.7 V	1.2 V to 5.5 V	5 pF	10 kΩ	≤3.0 ns	V_{CCI}	0 V	$2V_{CCO}$

12. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

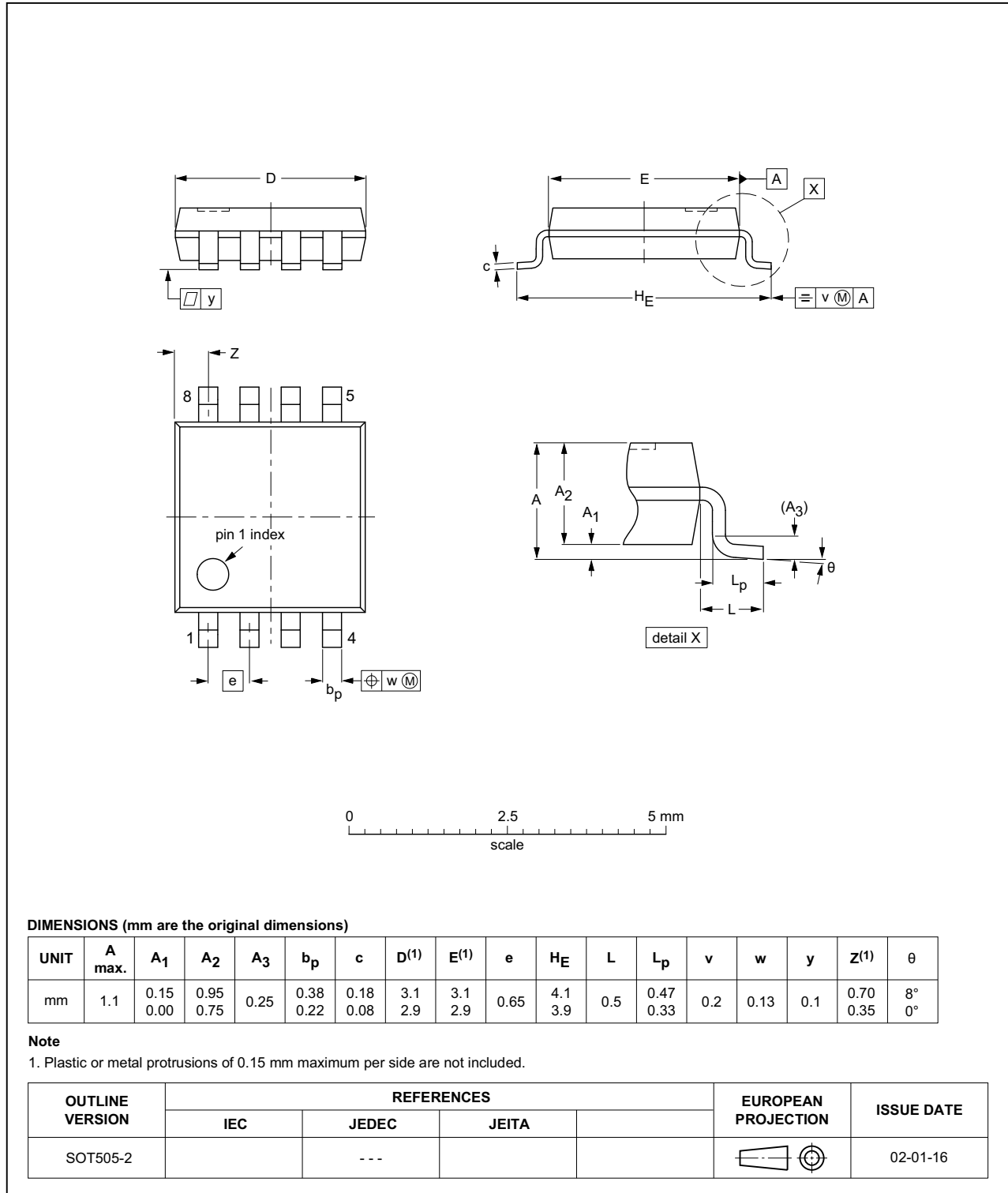


Fig 14. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

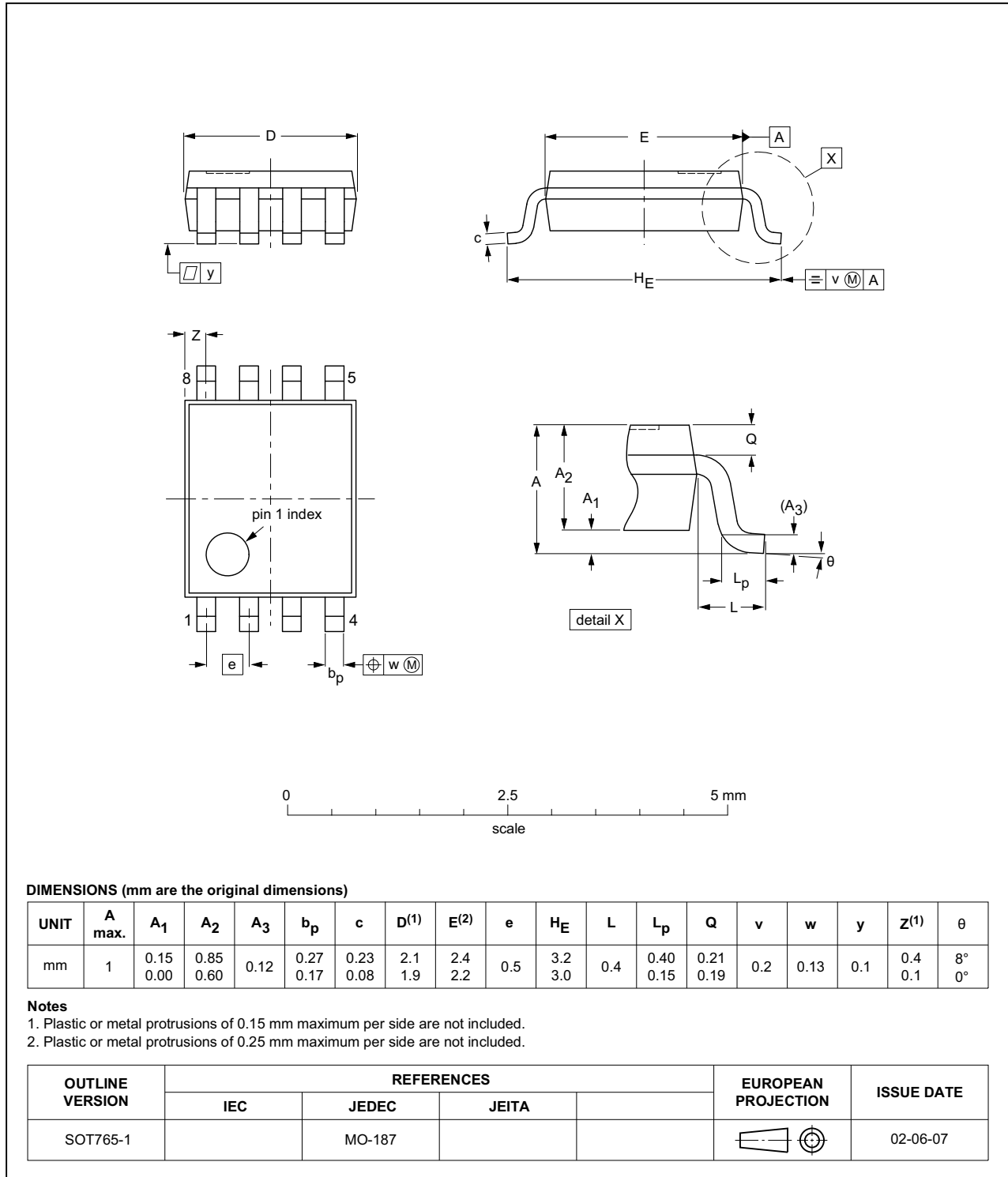


Fig 15. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads; 8 terminals; body 1 x 1.95 x 0.5 mm

SOT833-1

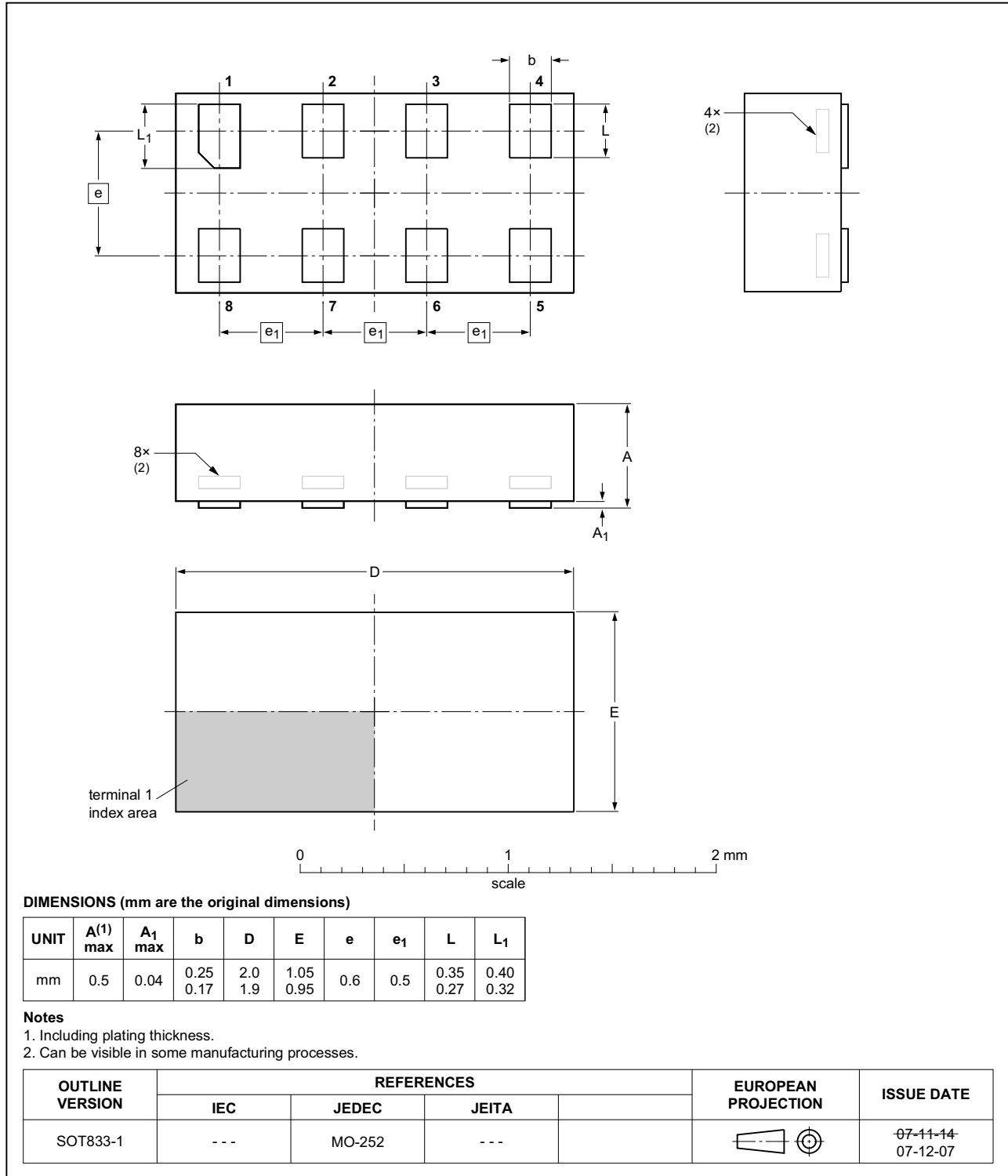


Fig 16. Package outline SOT833-1 (XSON8)

XSON8: plastic extremely thin small outline package; no leads;
8 terminals; body 3 x 2 x 0.5 mm

SOT996-2

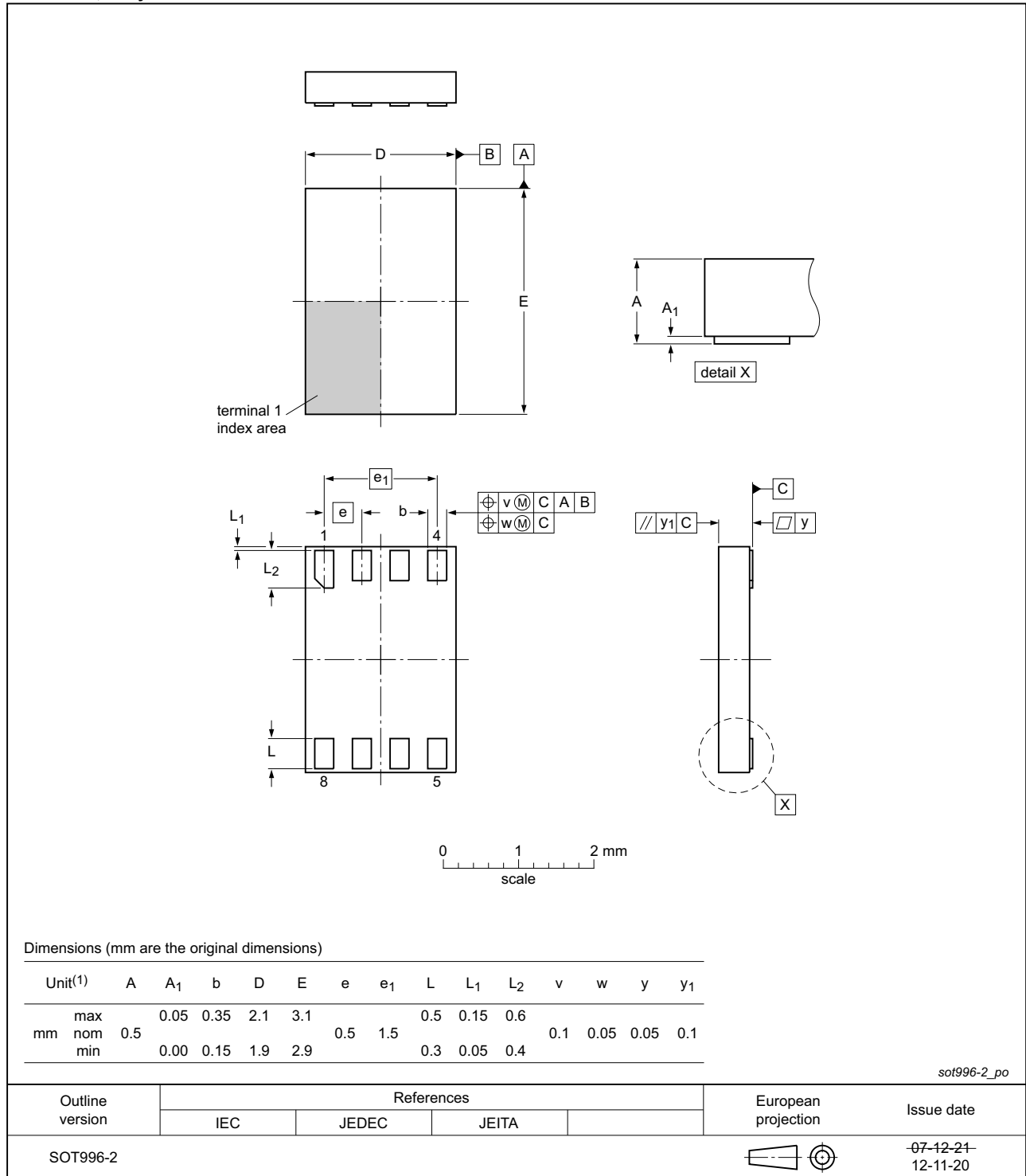


Fig 17. Package outline SOT996-2 (XSON8)

XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.2 x 1.0 x 0.35 mm

SOT1116

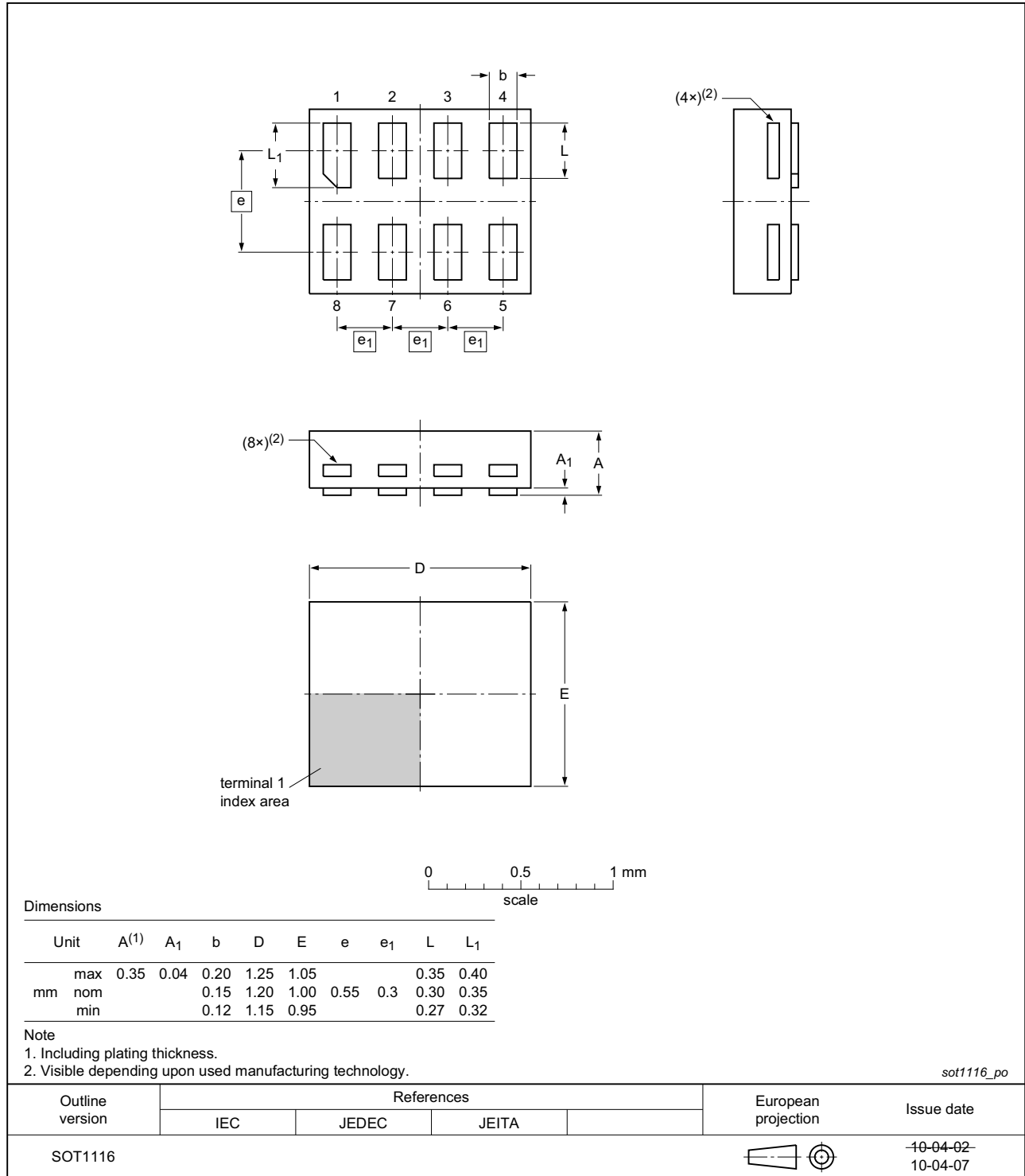


Fig 18. Package outline SOT1116 (XSON8)

XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.35 x 1.0 x 0.35 mm

SOT1203

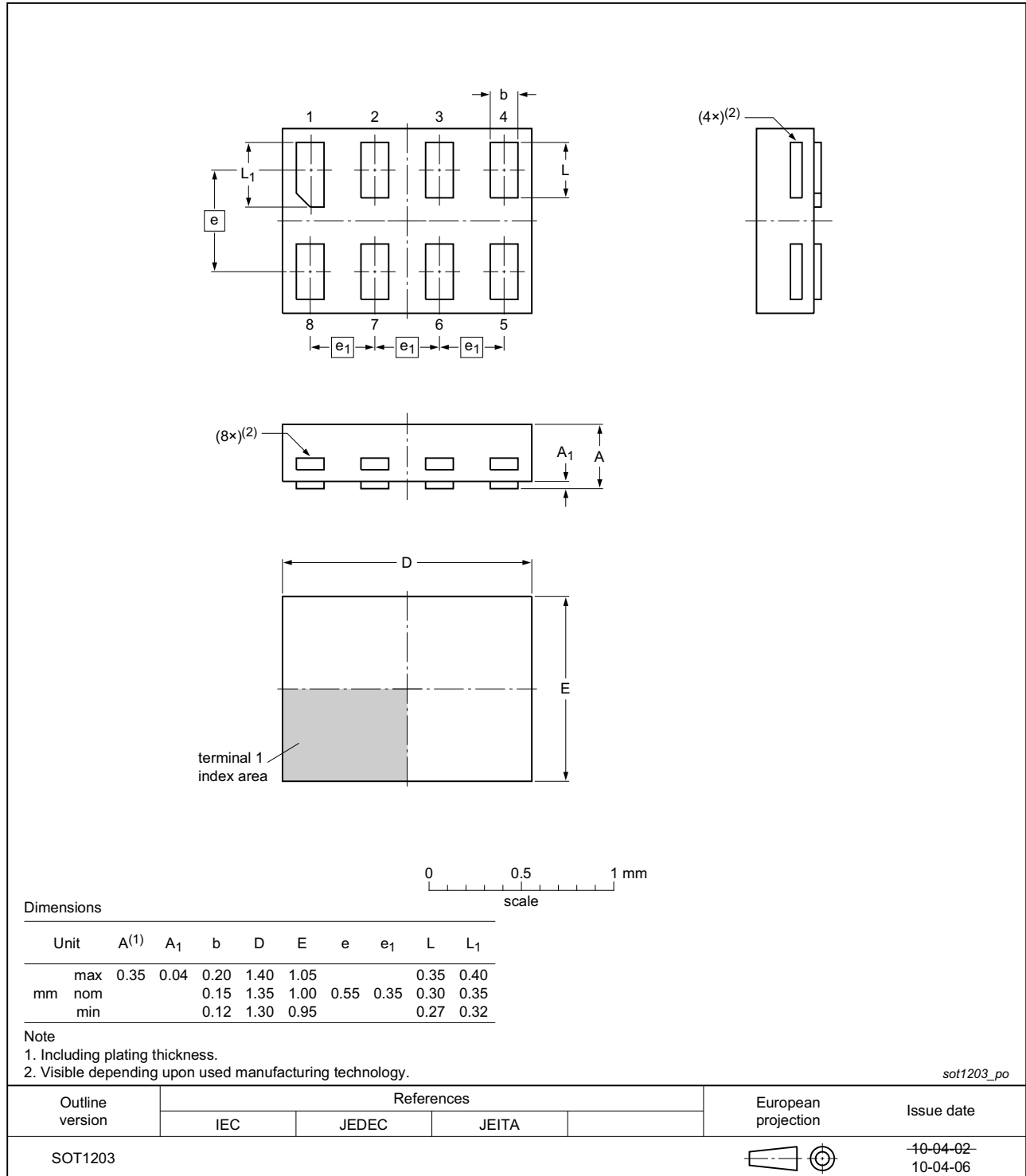


Fig 19. Package outline SOT1203 (XSON8)

13. Abbreviations

Table 16. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model

14. Revision history

Table 17. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AXP2T3407 v.1	20151221	Product data sheet	-	-

15. Legal information

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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